

BRIDGING METHOD OF INTERCONNECTS FOR
INTEGRATED CIRCUIT PACKAGES

ABSTRACT OF THE DISCLOSURE

An integrated circuit package (30) having first and second layers (76, 78), a plurality of routing pads (82) being integral with the first layer (76), a plurality of upper and lower conduits (18, 118), respectively, disposed on the upper and lower surfaces (92, 94) of the first layer (76), at least one of the upper conduits (18) electrically connected to at least one of the lower conduits (118), a plurality of pads (100) disposed on the second layer (78), vias (84) that electrically connect the pads (100) to the lower conduits (118) and a chip (50) adhered to the second layer (78) having bonding pads (120) at least one of which is electrically connected to at least one of the routing pads (82), is disclosed.

This Sheet Has Been Replaced

